

Encapsulant Application Questions

1. What is the type and size of the component that you are encapsulating?
2. What is the type and size of the substrate?
3. How big of an area is to be filled?
4. What is the gap thickness/height to underfill? (Between the component and the substrate)?
5. What is the height of the component?
6. What is the required maximum thickness of the encapsulant?
7. Is cleaning performed prior to encapsulating?
8. Is a dam desired for flow control?
9. What is the operating temperature of your application?
10. Is the component going to be subjected to reflow temperature?
11. What is the end/ final product?
12. What is your estimated monthly/ yearly volume? (how much of the encapsulant material will you be using per month?)